



Access



Evolution



Productivity

IBS-E

ICC Backside Spot Pressure Test Tool

Applications

The ICC Backside Spot Pressure test tool (left side on the picture) is designed to test the IC Module adhesion resistance into the card body. It complies to the latest MasterCard CQM requirements (#8230# test method). This test is a destructive test with concentrated pressure on the reverse center side of the contact location.

- IC module adhesion qualification.
- Quality control / Production control.
- Support to CQM certification and audit.

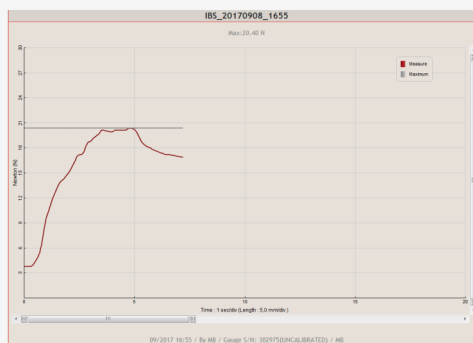
Key benefits

This version comes with digital gauge connected to a PC and a dedicated utility.

- Easy-to prepare the opening into the card body with a dedicated accessory tool to drill an opening.



Preparation tool



Technical characteristics

Max gauge force
500 N (Newtons)

Accessories
Preparation tool included

Dimensions
W x D x H: 190 x 235 x 380 mm

Weight
11,6 Kg

In compliance with E.C. directives

Associated products

Other MULANN products are nicely complementary:

- BWT-A or WTT-A control tools for bending stiffness and wrapping test
- TFD-A or TFD-P30 testers for dynamic bending